

L Number	Hits	Search Text	DB	Time stamp
1	707311	ball or bump or solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/10 07:24
2	9546	pressure adj weld\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/10 07:24
3	879	(ball or bump or solder) and (pressure adj weld\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/10 07:24
4	841114	chip or die	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/10 07:25
5	283	((ball or bump or solder) and (pressure adj weld\$4)) and (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/10 07:39
6	3	"6553660"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/10 08:02
7	479	438/109.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/10 08:03
8	328	438/109.ccls. and (ball or bump or solder)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/10 08:04
9	3	(438/109.ccls. and (ball or bump or solder)) and (pressure adj weld\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/10 08:03
10	325	(438/109.ccls. and (ball or bump or solder)) not ((438/109.ccls. and (ball or bump or solder)) and (pressure adj weld\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/10 08:09
11	2	("5973403").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/10 08:11
12	2970461	pressure	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/10 08:11
13	0	("5973403").PN.) and pressure	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/10 08:12
14	4	("5696036") or ("20020045290").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/10 08:14

15	4	{{("5696031") or ("20020045290")}.FN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT	2003/10/10 08:14
16	21	(("4447857"   "4567643"   "4991000"   "5228192"   "5252857"   "5291064"   "5311059"   "5323060"   "5355283"   "5399898"   "5399903"   "5422435"   "5434745"   "5436203"   "5467253"   "5468999"   "5495398"   "5502289"   "5508561"   "5514907"   "5527740").FN.		2003/10/10 08:18
17	28	5696031.URPN.	USPAT	2003/10/10 08:21
18	28	5696031.URPN.	USPAT	2003/10/10 08:28